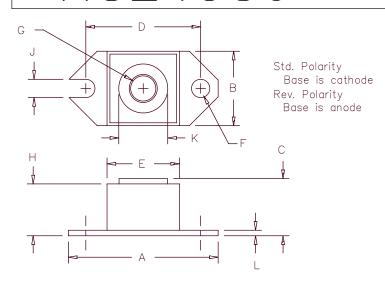
# 240 Amp Schottky Rectifier HS243100



Dim.	. Inches Millimeter				
	Minimum	Maximum	Minimum	Maximum	Notes
A B C D E F	1.52 .725 .605 1.182 .745	1.56 .775 .625 1.192 .755 .160	38.61 18.42 15.37 30.02 18.92 3.86	39.62 19.69 15.88 30.28 19.18 4.06	Sq. Dia.
H J K L	.525 .156 .495 .120	.580 .160 .505 .130	13.34 3.96 12.57 3.05	14.73 4.06 12.83 3.30	Dia.

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage
HS24380*	243NQ080	80V	80V
HS24390*	MBR24080	90V	90V
HS243100*	243NQ100 MBR240100	100V	100V
	*Add Suffix R	for Reverse Polarit	V

- Schottky Barrier Rectifier
- Guard Ring Protection
- 240 Amperes/80 to 100 Volts
- 175°C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

### Electrical Characteristics

F(AV) 240 Amps Average forward current Maximum surge current FSM 3300 Amps Maximum repetitive reverse current R(OV) 2 Amps Max peak forward voltage VFM 0.72 Volts  $V_{\mathsf{FM}}$ Max peak forward voltage 0.86 Volts Max peak reverse current <sup>I</sup>RM 200mA Max peak reverse current 1<sub>RM</sub> 8.0mA Typical junction capacitance  $C_{\mathsf{J}}$ 6400pF

 $^{T}C = 122^{\circ}C$ , Square wave, $^{R}\Theta JC = .24^{\circ}C/W$ 8.3ms, half sine,  $^{T}J = 175^{\circ}C$  f = 1 KHZ, 25 $^{\circ}C$ 

|FM| = 240A: |TJ| = 175°C\* TFM = 240A: TJ = 25°C\* VRRM, TJ = 125°C\*

VRRM, TJ = 25°C  $VR = 5.0V, TC = 25^{\circ}C$ 

\*Pulse test: Pulse width 300 µsec, Duty cycle 2%

### Thermal and Mechanical Characteristics

Storage temp range Operating junction temp range Max thermal resistance Typical thermal resistance (greased) Terminal Torque Mounting Base Torque Weight

ΤĴ R OJC Recs

-55°C to 175°C -55°C to 175°C 0.24°C/W Junction to case

0.12°C/W Case to sink 35-40 inch pounds 20-25 inch pounds

1.1 ounces (32 grams) typical



## HS24380 HS243100

Figure 1 Typical Forward Characteristics

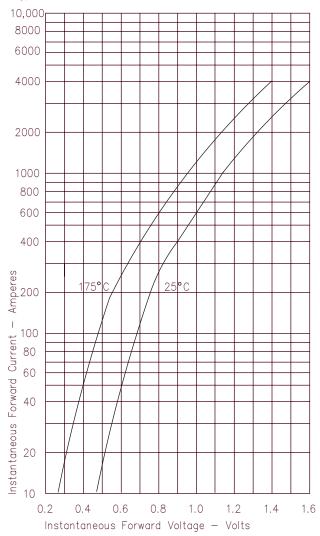


Figure 3 Typical Junction Capacitance

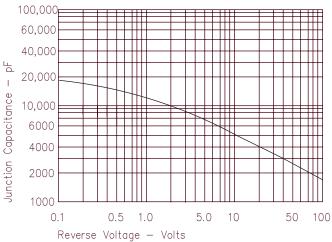


Figure 4

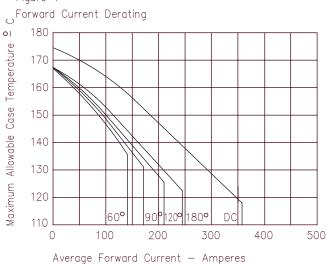


Figure 2 Typical Reverse Characteristics

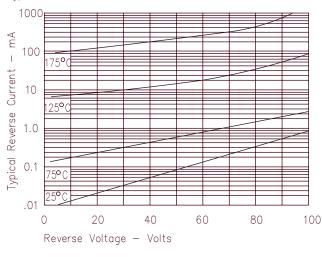
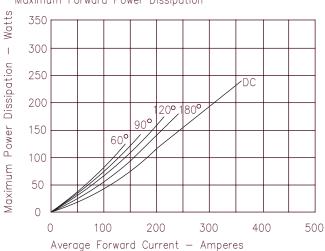


Figure 5 Maximum Forward Power Dissipation

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